



Typical Properties		
	Typical Values	Test Condition
Thermal		
Tg (DMA) Tg (TMA) Td (TGA)	240 °C 200 °C 430 °C	E-2/105+des
CTE α1 CTE α2 CTE z-axis	35 ppm/°C 200 ppm/°C 2.0%	Ambient to Tg Ambient to Tg 50 to 260°C
Thermal Stress, Solder Float, 288°C	> 60 sec	A
T-260 T-288 T-300	> 60 min > 60 min > 60 min	E-2/105+des
Flammability	94V-0	E-24/125+des
Electrical		
Permittivity (RC64%) 10GHz (SPC method) 20GHz (SPC method)	3.25 3.24	C-24/23/50
Loss Tangent (RC64%) 10GHz (SPC method) 20GHz (SPC method)	0.0018 0.0020	C-24/23/50
Volume Resistivity	> 10 ¹⁰ MΩ·cm	C-96/35/90
Surface Resistivity	> 10 ⁸ MΩ	C-96/35/90
Electric Strength	> 40 KV/mm	-
Dielectric Breakdown Voltage	> 50 KV	-
Mechanical		
Young's Modulus Warp Direction Fill Direction	31 GPa 29 GPa	A
Flexural Strength Lengthwise Crosswise	> 60,000 psi > 50,000 psi	A A
Peel Strength, 1.0 oz. Cu foil	4~6 lb/in	A
Water Absorption	0.08 %	E-1/105+des+D-24/23

NOTE:

1. Property values are for information purposes only and not intended for specification.
2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
3. This product is based on a patent pending technology.